

**Flangeless Mount Termination
150 Watts, 50Ω**



Description

The E150N50X4 is high performance Aluminum Nitride (AlN) termination intended as a cost competitive alternative to Beryllium Oxide (BeO). The termination is well suited to all cellular frequency bands such as; AMPS, GSM, DCS, PCS, PHS and UMTS. The high power handling makes the part ideal for terminating circulators, and for use in power combiners. The termination is also RoHS compliant!

Features:

- RoHS Compliant
- 150 Watts
- DC – 2.7 GHz
- AlN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications:

Resistive Element	Thick film
Substrate	AlN Ceramic
Terminal Finish	Matte Tin over Nickel
Cover	Alumina Ceramic

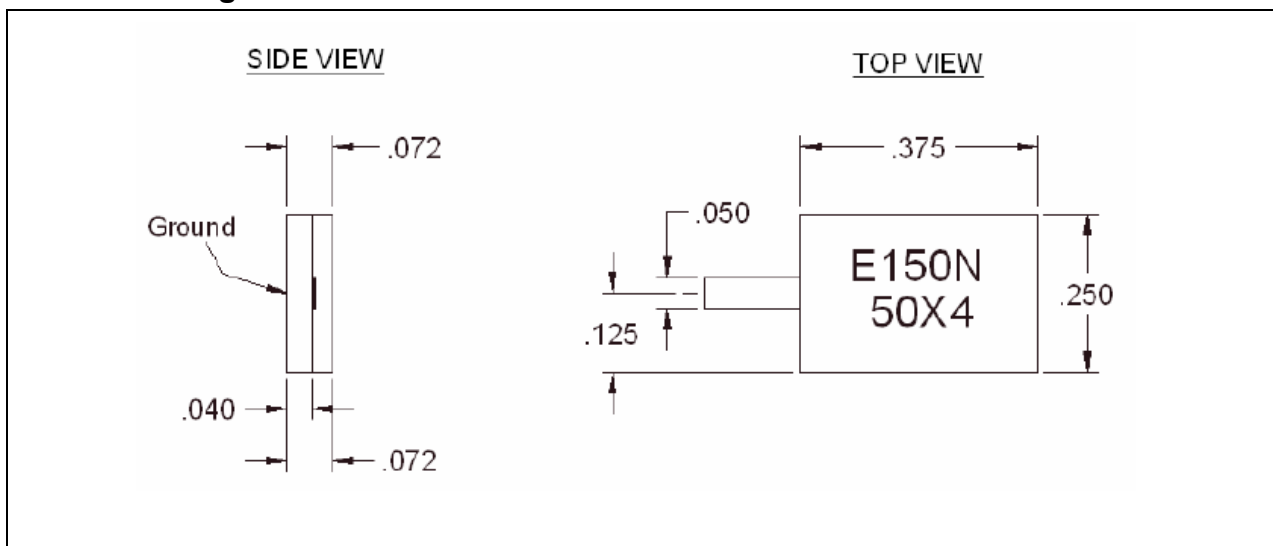
Tolerance is ± 0.010 ", unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions in inches.

Electrical Specifications:

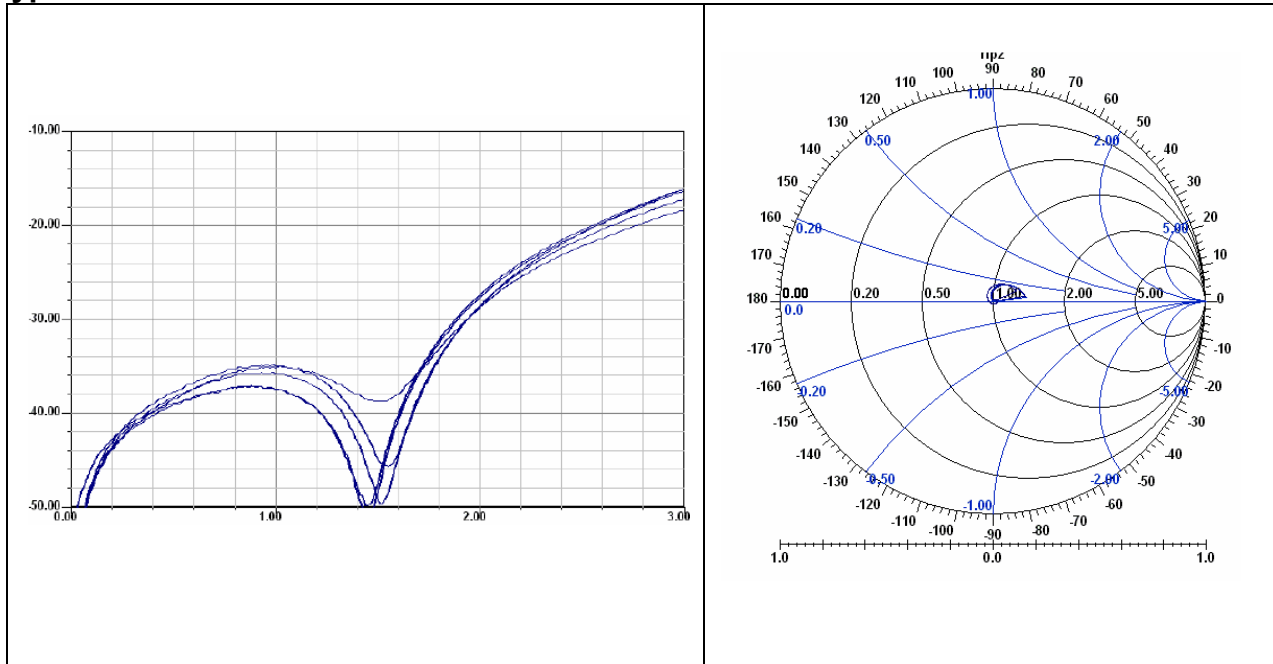
Resistive Value:	50 Ohms \pm 2%
Power:	150 Watts
Frequency Range:	DC – 2.7 GHz
Return Loss	> 25 dB DC – 2.0 GHz > 20 dB DC – 2.7 GHz

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

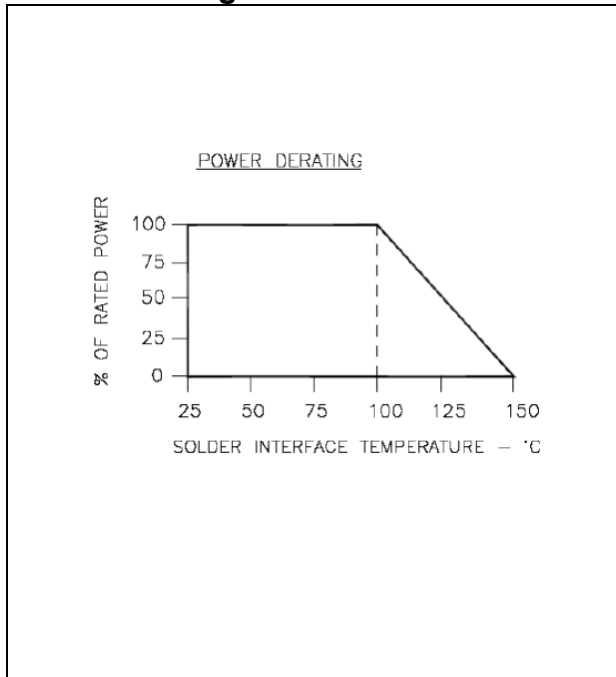
Outline Drawing:



Typical Performance:



Power De-rating:



Mounting Footprint and Procedure

0.025 MIN (2 PLACES)

BOARD LOWER THAN LEAD BOARD EVEN WITH LEAD BOARD LOWER THAN LEAD BOARD HIGHER THAN LEAD

SUGGESTED STRESS RELIEF METHODS NOT RECOMMENDED APPLICATION

SCALE: NONE SCALE: NONE

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING LEAD FREE TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON

** FOR MORE DETAILS CONTACT FACTORY **

Contact us:
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